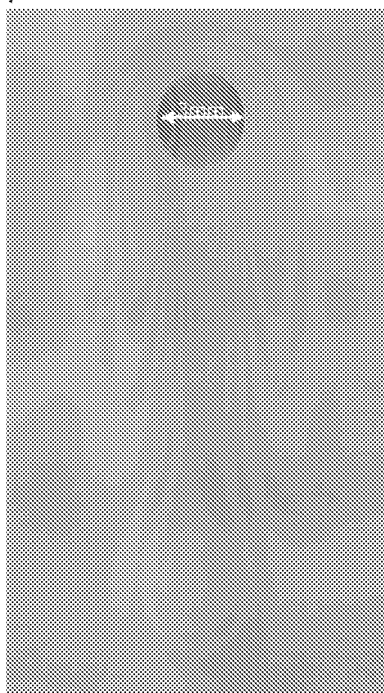


[図1]

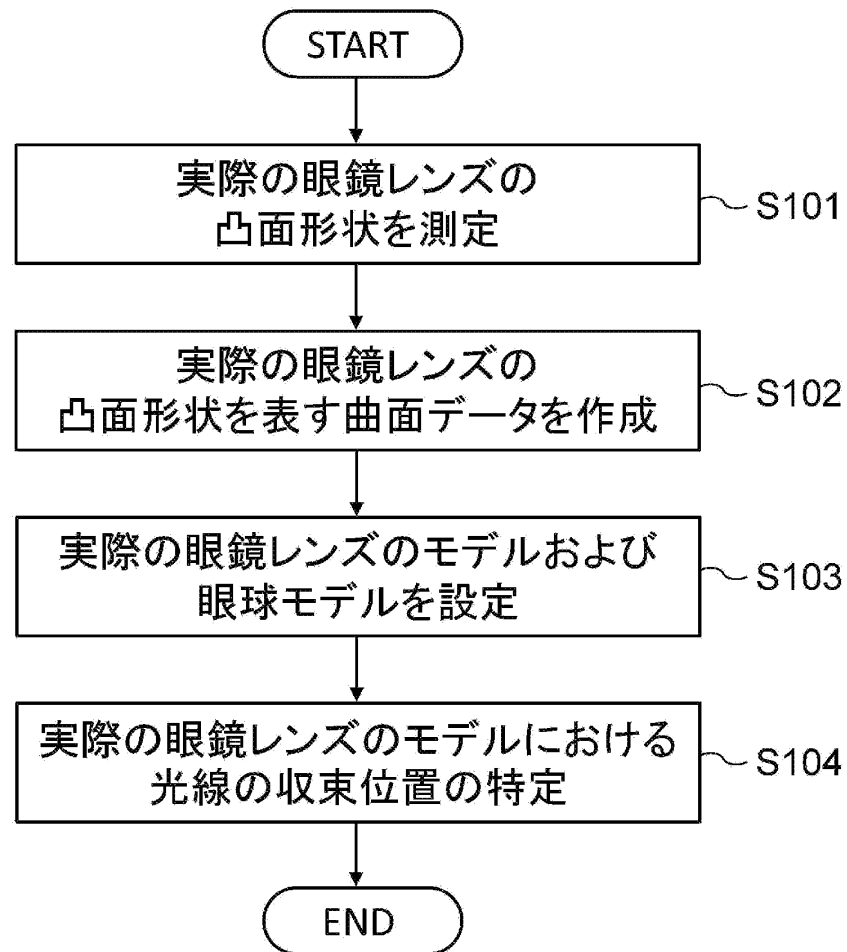
(a)



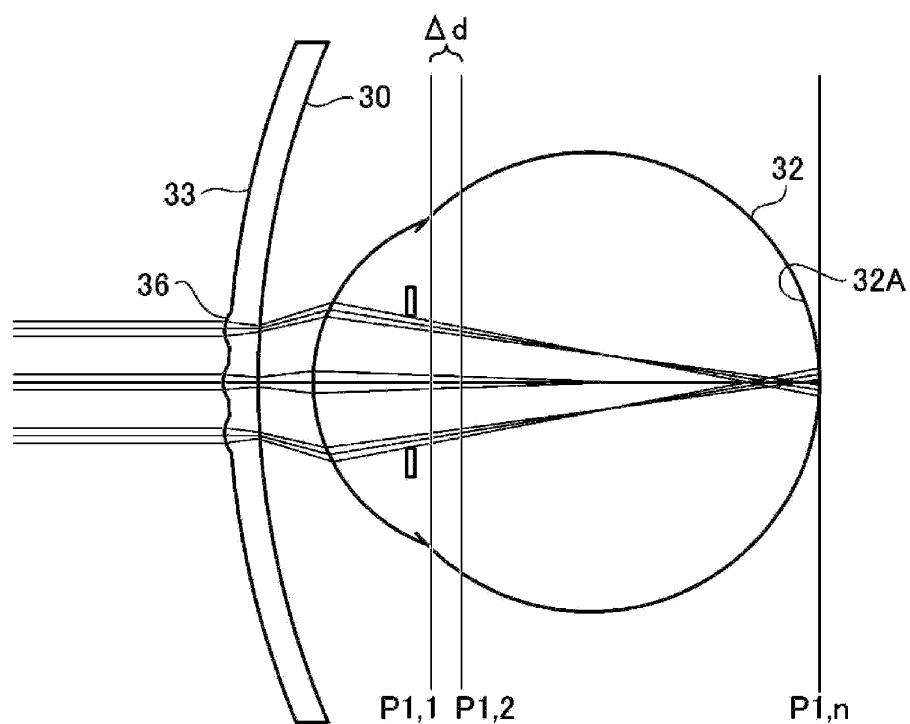
(b)



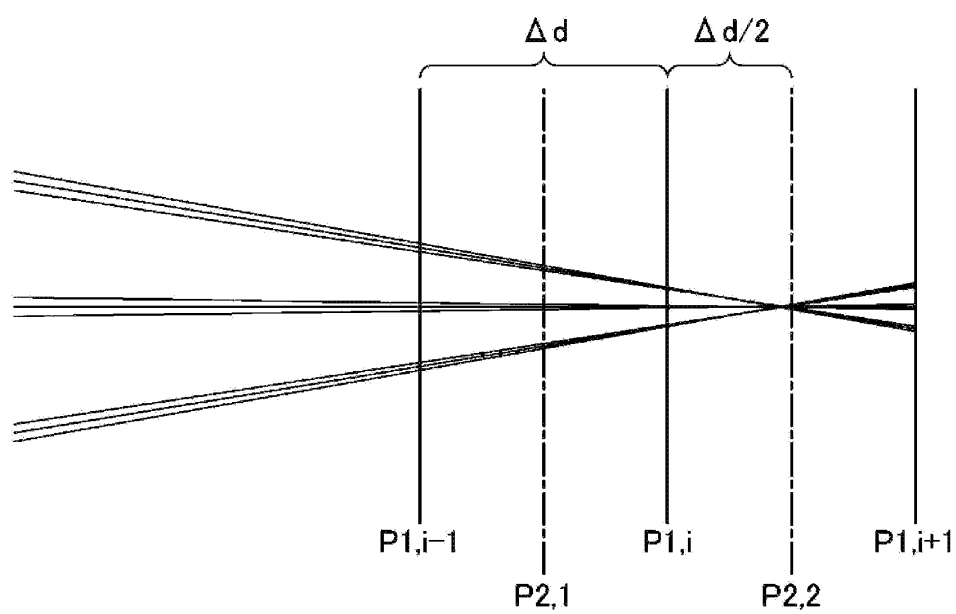
[図2]



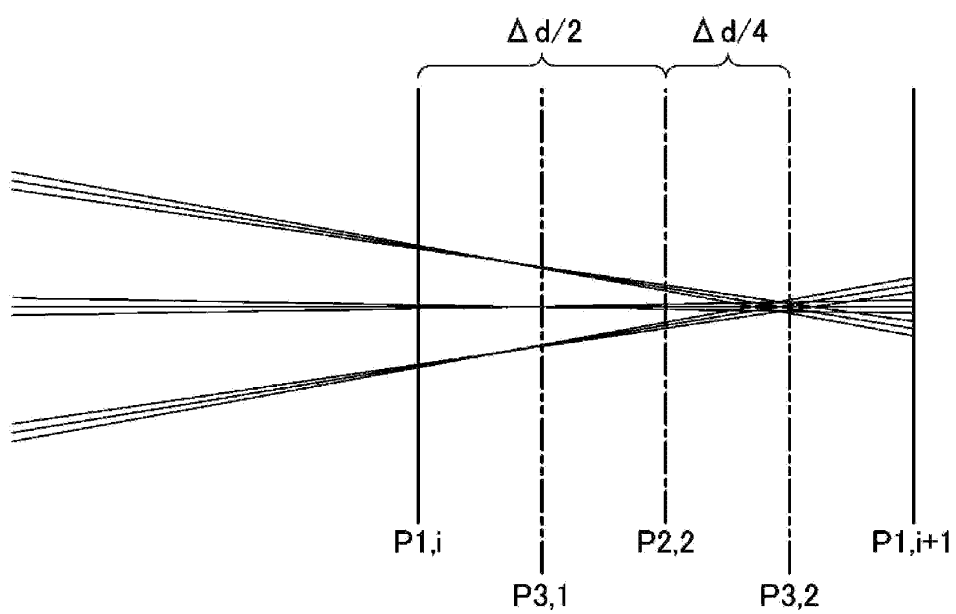
[図3]



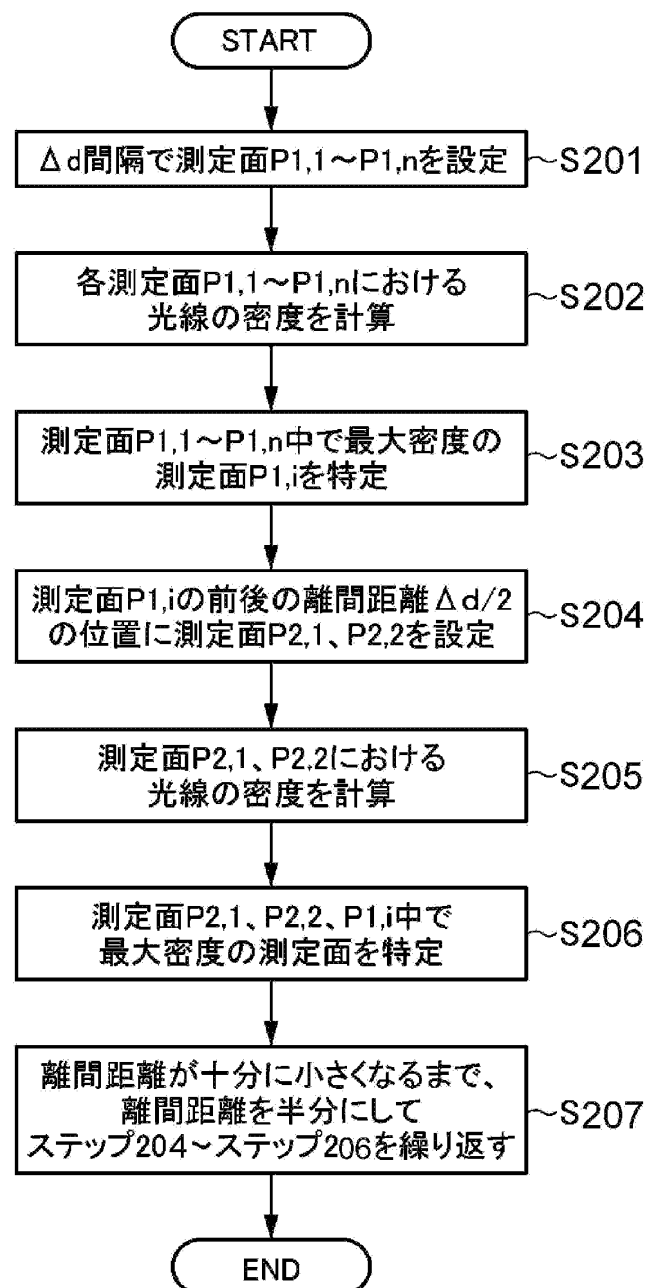
[図4]



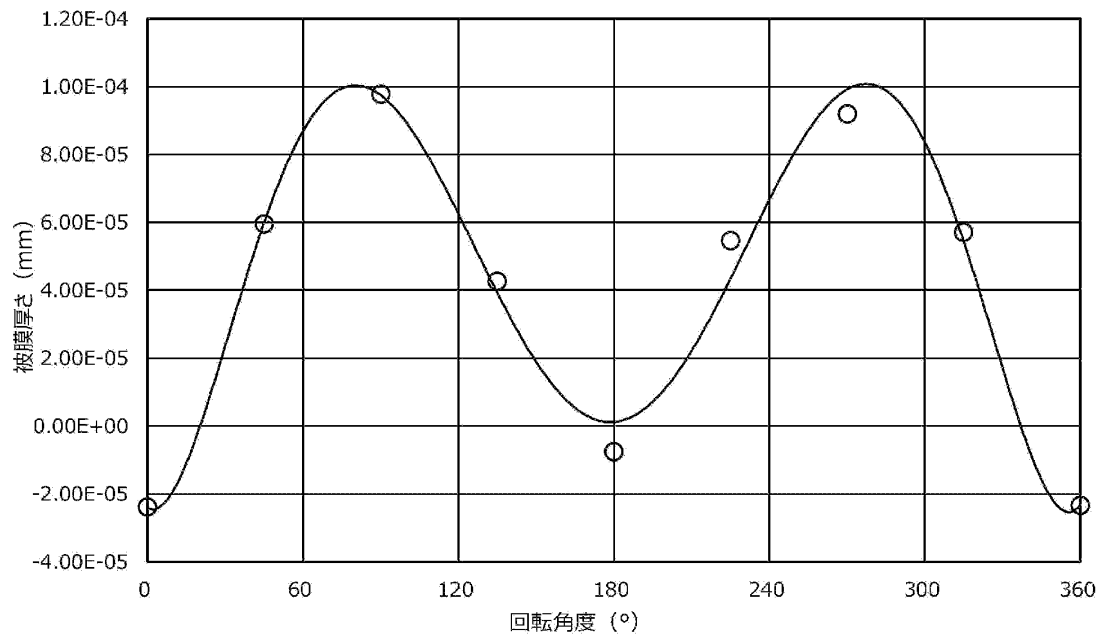
[図5]



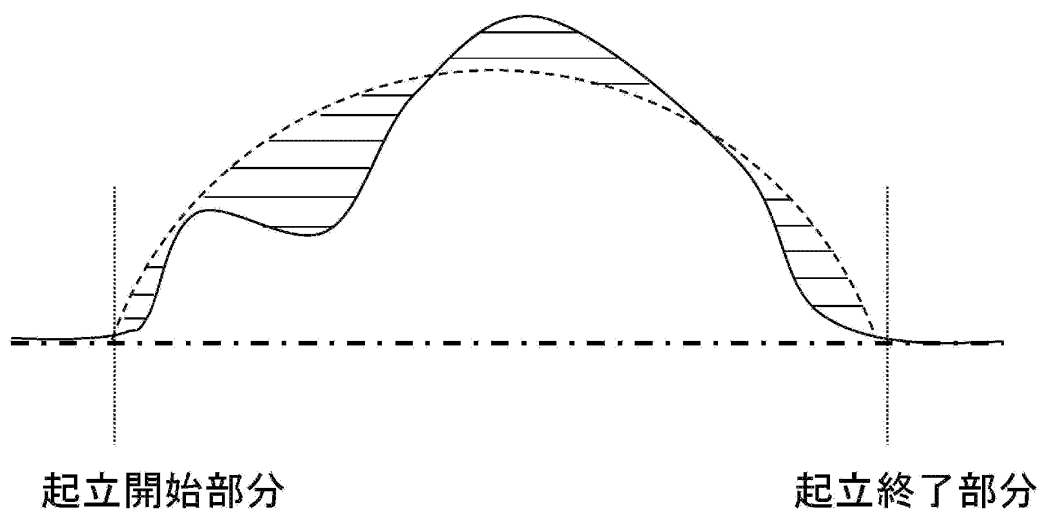
[図6]



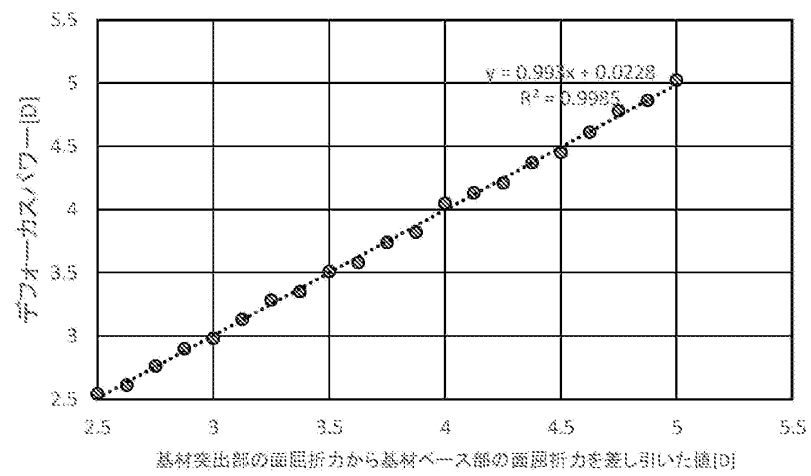
[図7]



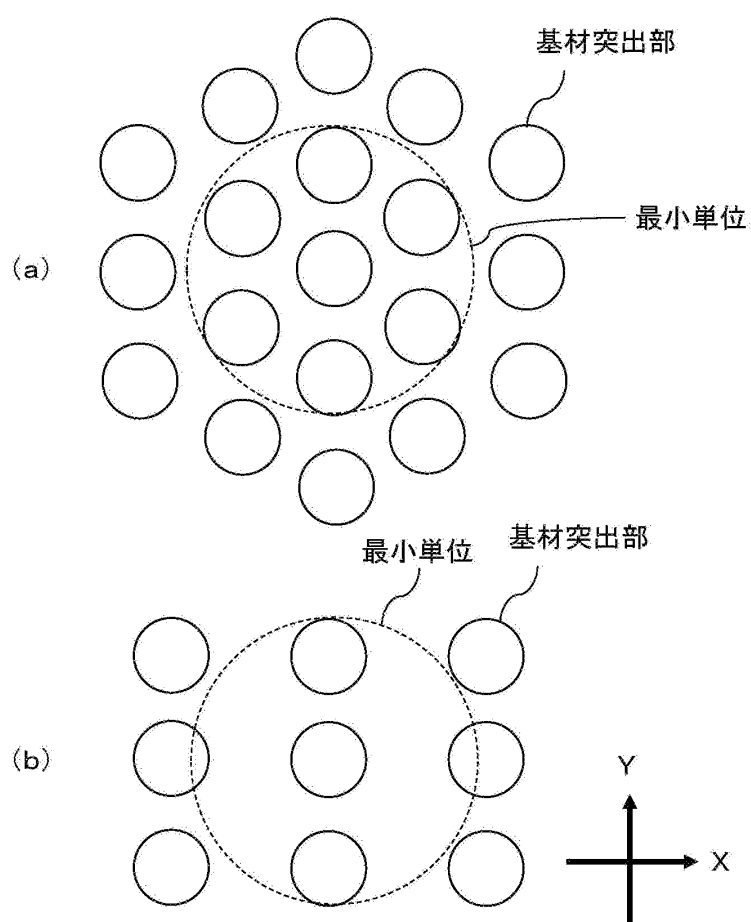
[図8]



【図9】



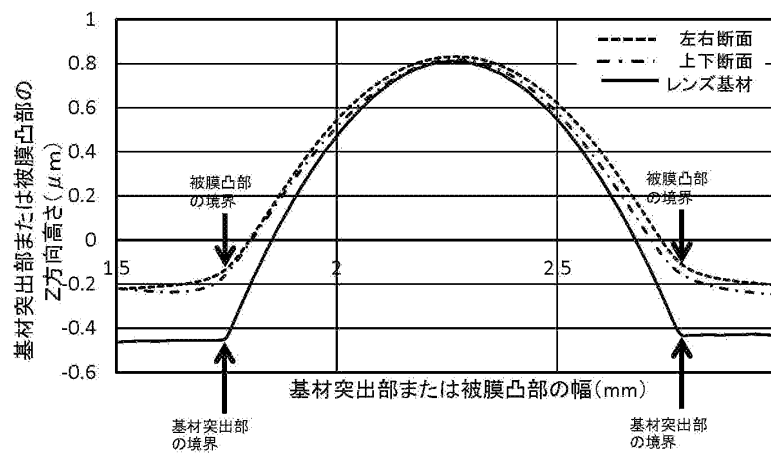
[図10]



[図11]

実施例6

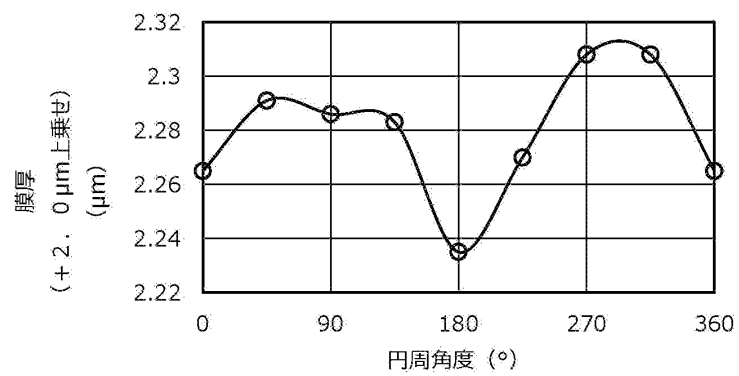
基材突出部のデフォーカスパワー: 5.50D
被膜ベース部の被膜の厚さ: 3.0 μm



[図12]

実施例7

基材突出部のデフォーカスパワー: 5.50D
被膜ベース部の被膜の厚さ: 2.0 μm



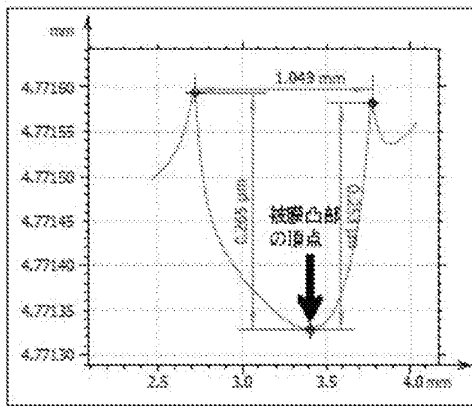
[図13]

実施例7

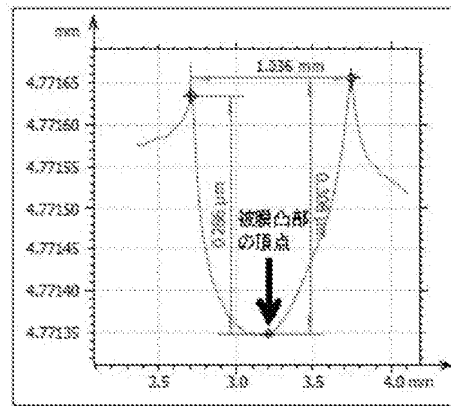
基材突出部のデフォーカスパワー: 5. 50D

被膜ベース部の被膜の厚さ: 2. 0 μm

(a) 左右断面



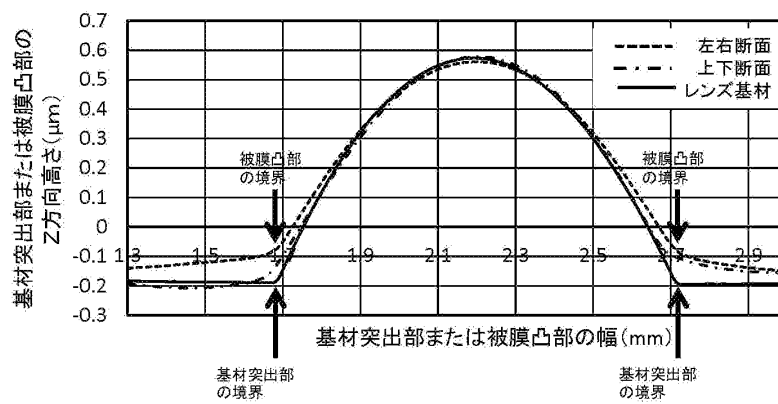
(b) 上下断面



[図14]

実施例8

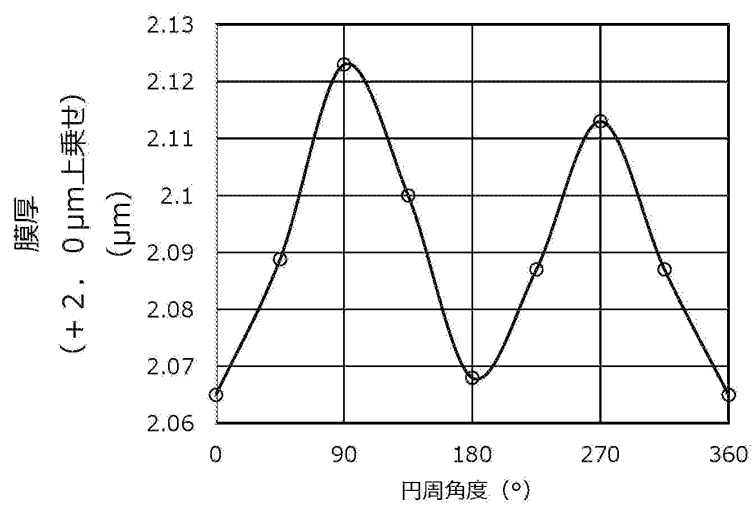
基材突出部のデフォーカスパワー:3.50D
被膜ベース部の被膜の厚さ:1.5 μm



[図15]

実施例9

基材突出部のデフォーカスパワー: 3.50D
被膜ベース部の被膜の厚さ: 2.0 μm



[図16]

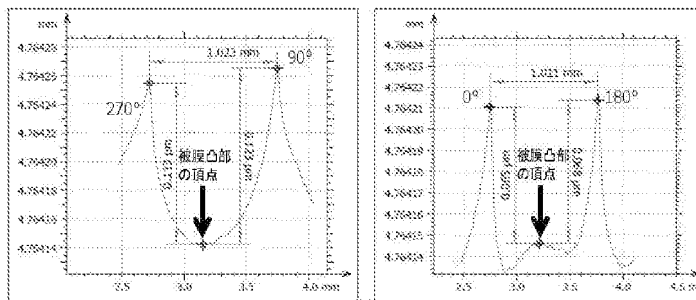
実施例9

基材突出部のデフォーカスパワー: 3.50D

被膜ベース部の被膜の厚さ: 2.0 μm

(a) 左右断面

(b) 上下断面



[図17]

